SmartTrim™ MEMS Microphone with I2S/TDM for Microphone Array

DESCRIPTION

The ZTS6672 is a high quality, low cost, low power digital output bottom-ported omni-directional MEMS microphone. ZTS6672 consists of a MEMS microphone element and a preamplifier. ZTS6672 has a high SNR and flat wideband frequency response, resulting in natural sound with high intelligibility. Due to built-in filter, ZTS6672 shows high immunity to EMI.

The ZTS6672 is available in a thin 3.50mm × 2.65mm × 0.98mm surface-mount package. It is reflow solder compatible with no sensitivity degradation. The ZTS6672 is halide free.

APPLICATIONS

- Small portable devices, wearables
- Set-top boxes, TV, gaming, remote controllers
- Smart home devices, Internet of Things, Connected equipment

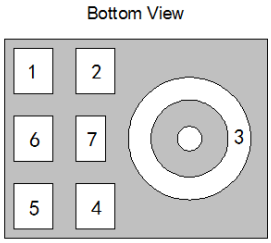
ORDERING INFORMATION

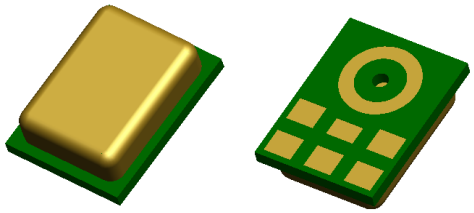
PART	RoHS	Ship, Quantity
ZTS6672	Yes	Tape and Reel, 5.2K

FEATURES

- Audio data Slave I2S or time division multiplexed (TDM) output interface
- Configurable TDM slots, support upto 8 format
- Supply operation: 1.60 V to 3.60V
- 64×/128×/192×/256×/384×/512× output sample rate BCLK
- Automatic CLK ratio detection
- Output sample rate: 4 kHz to 96 kHz
- SNR of 64.5dB(A)
- Sensitivity of −26 +/-1dBFS with 2nd Generation SmartTrim™ Technology
- Multi Chip Module (MCM) Package 3.50mm×2.65mm×0.98mm surface-mount package

Pins Configuration and Description





Top Bottom

Isometric Views of ZTS6672 Microphone Package

Typical Applications

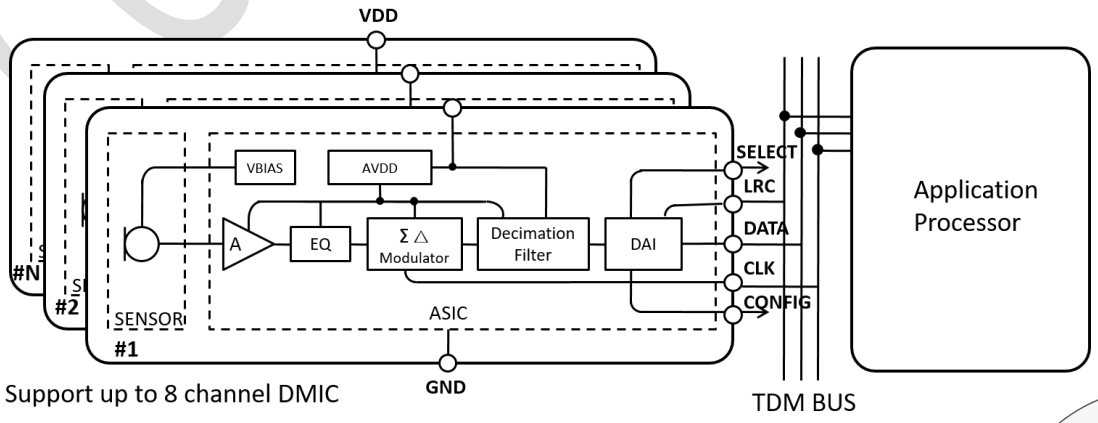


Figure.1 Application Diagram

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Absolute Maximum Ratings

CLOCK to Ground ..... –0.3V to +6.0V
SELECT, V_{DD}, DATA to Ground ..... –0.3V to +6.0V
Input Current ..... ±5mA
Data Output Short Circuit ..... Indefinite to Ground or V_{DD}
Operating Temperature Range ..... –40°C to +100°C
Storage Temperature Range ..... –40°C to +100°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

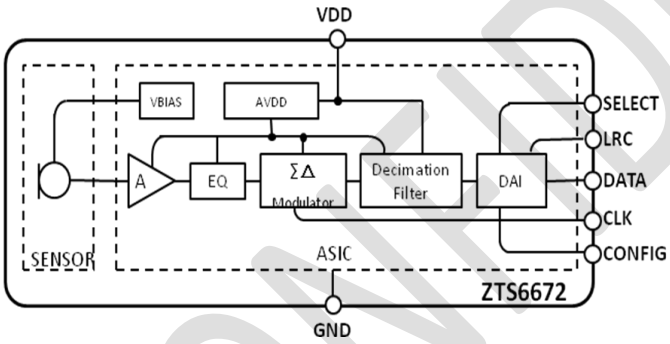
Electro-Static Discharge Sensitivity

This integrated circuit can be damaged by ESD. It is recommended that all integrated circuits be handled with proper precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure.

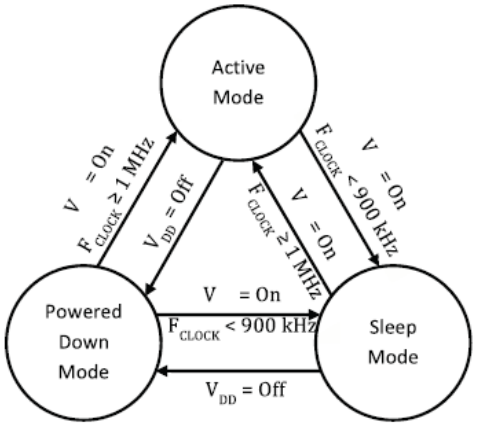
Pins Description

Pin	Symbol	Description
1	LRC	Frame Sync
2	SELECT	Select.
3	GND	Ground
4	BCLK	Bit Clock
5	VDD	Power Supply (VDD).
6	DATA	Output.
7	CONFIG	Interface Configuration

Microphone Block Diagram



Microphone State Diagram



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Specifications

(Table 2: TEST CONDITIONS: 25°C, 55±20% R.H ., VDD =1.8V, BCLK=3.072MHz with 0 .1uF decoupling capacitor across Vdd and GND,)

PARAMETER	Symbol	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Supply Voltage (Note 1)	VDD		1.60		3.60	V
Current Consumption (Note 1,5,6)	IDD			1000	1200	µA
Sleep Current (Note 6)	ISLEEP	fclock < 1KHz			10	µA
Directivity			Omni-directional			
Sensitivity (Note 1)	S	94dB SPL @ 1KHz	−27	−26	−25	dB FS
Signal to Noise Ratio	SNR	94dB SPL @ 1KHz, A-weighted		64.5		dB(A)
Total Harmonic Distortion	THD	115dB SPL @ 1KHz			1	%
		120dB SPL @ 1KHz			10	%
Acoustic Overload Point	AOP	10% THD @ 1 kHz, S = Typ.		120		dB SPL
Power Supply Rejection Ratio	PSRR	200 mVpp sine wave@1kHz		60		dB
Power Supply Rejection	PSR+N	217Hz, 100mV Vp-p, square wave on VDD		−86		dB FS
Short Circuit Output Current	ISC	Grounded output pin	2		10	mA
Sleep Current	Iddsleeep				10	uA
Output Load	CLOAD				120	pF
Data Format			24bits			
Clock Frequency	fclock		2.048		4.096	MHz
Sleep Clock Frequency	fsleep				900	KHz
Clock Duty Cycle			40		60	%
Clock Rise/Fall Time	tedge				13	ns
Logic Input Low	VIL		−0.3		0.35×VDD	V
Logic Input High	VIH		0.65×VDD		VDD+0.3	V
Logic Output Low	VOL	Iout = 2mA	0		0.3×VDD	V
Logic Output High	VOH	Iout = 2mA	0.7×VDD		VDD	V
Low→High Threshold	VL-H		0.55×VDD		0.65×VDD	V
High→Low Threshold	VH-L		0.35×VDD		0.45×VDD	V
Hysteresis Width	VHYST		0.10×VDD		0.29×VDD	V
Data Time	tsetup	Measured from 0.1 to 0.9 VDD	10			ns
Functional Temperature		Functional with lower performance	-40		100	°C
Operating Temperature		Specifications guaranteed	0		45	°C
Power-up Time4,5		VDD ≥ V(min)			50	ms
SELECT (high)			VDD -0.2		VDD	V
SELECT (low)		GND			GND+0.2	V
Select Input	CSELECT				2	pF
Clock Input	CCLK				2	pF
Clock Duty Cycle			40	50	60	%
TIE Clock Jitter	TIE	Time Interval Jitter on CLK line			2	ns RMS
Output Load	CLOAD				120	pF

Note 1: 100% tested.

Note 2: Valid microphone states are: Power Down Mode (mic off), Sleep Mode (low current, no output, Fast Start Mode).

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and Active Mode (normal operation).

Note 3: Time from fclock < 1KHz to sleep current specification is met when transitioning from Active to Sleep Mode.

Note 4: Time from fclock ≥ 1MHz to all applicable specifications are met when transitioning from Sleep to Active Mode.

Note 5: ΔIDD = 0.5 × VDD × CLOAD × fclock

Note 6: Specified max values are measured at VDD = +3.6V.

Timing Diagram

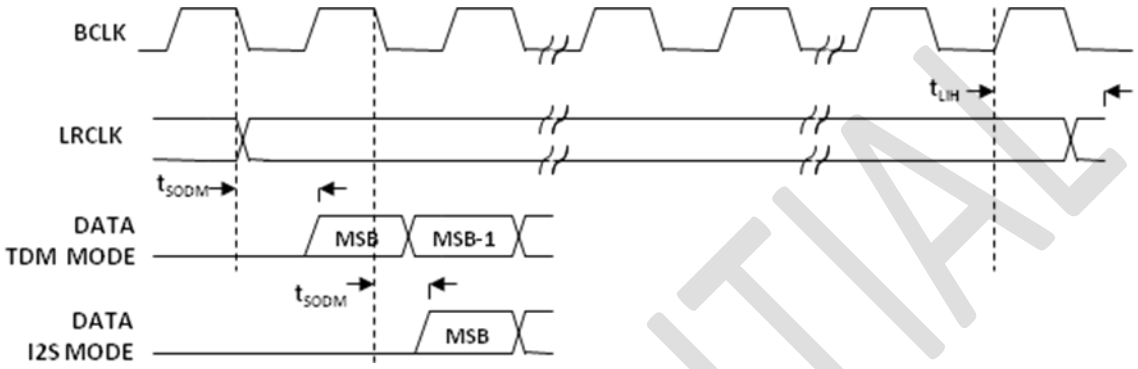

Figure 2: Timing Diagram

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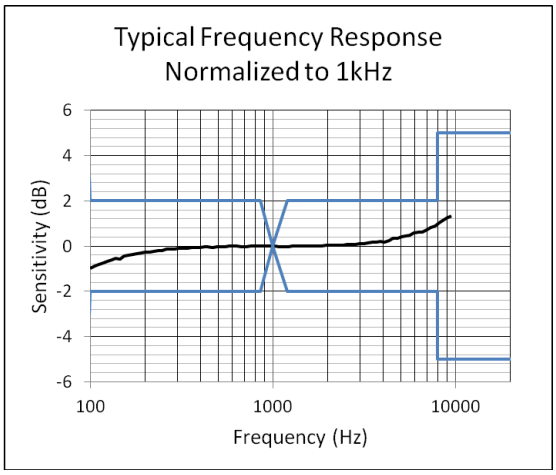
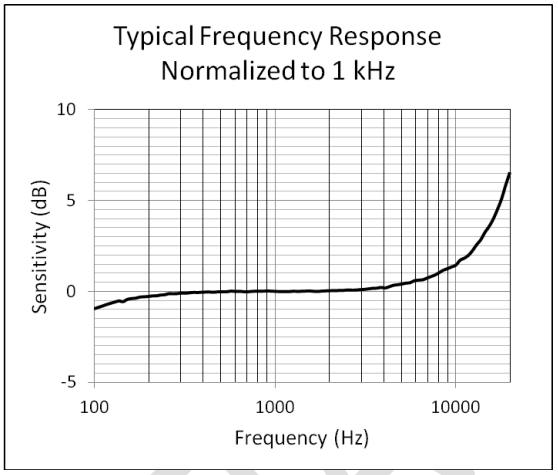
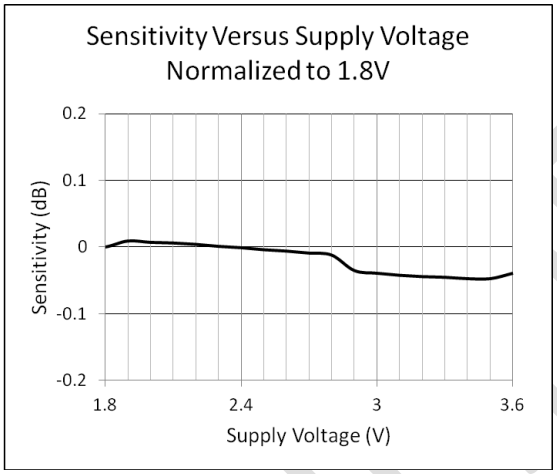
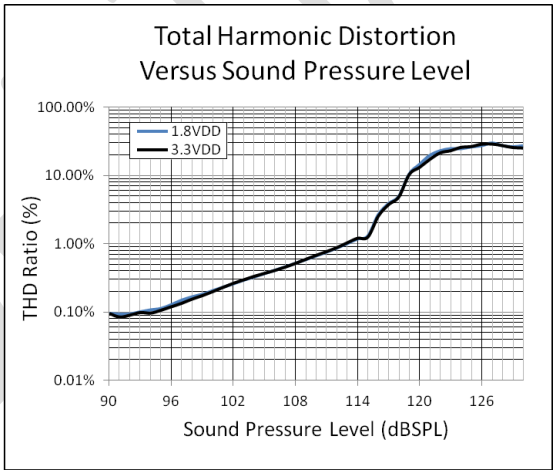
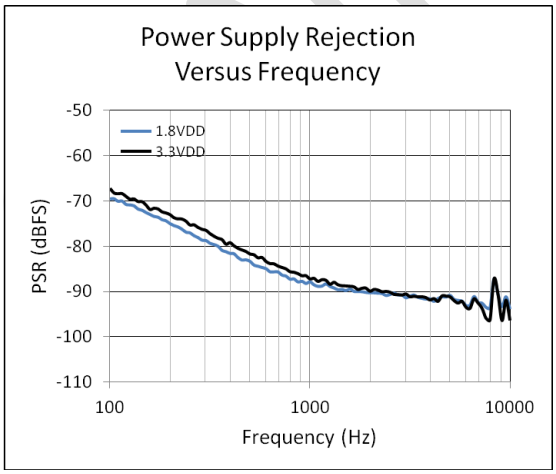
Typical Performance Characteristics

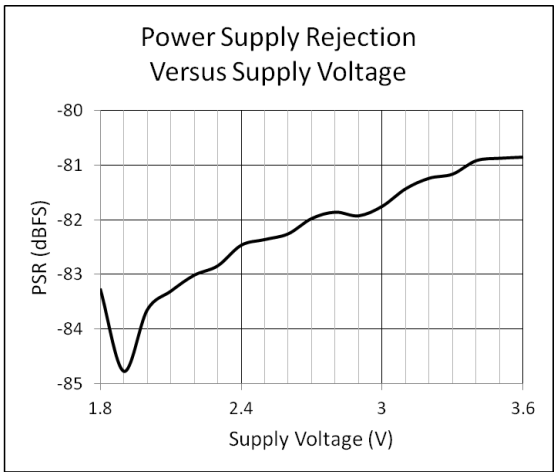












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Application Notes

SERIAL AUDIO OUTPUT INTERFACE

The ZTS6672 supports I2S and TDM serial output formats. Format selection and TDM slot placement is set with the CONFIG pin. The SDATA pin is in tristate mode, except when the port is driving serial data based on the CONFIG pin configuration.

CONFIG	SELECT	DEVICE SETTING
Open	Tight High	I2S Format Left Channel
	Tight Low	I2S Format Right Channel
Tight High	Tight High	TDM Slot 1
	Tight Low	TDM Slot 2
	Tight High with 47Kohm	TDM Slot 3
	Tight Low with 47Kohm	TDM Slot 4
Tight Low	Tight High	TDM Slot 5
	Tight Low	TDM Slot 6
	Tight High with 47Kohm	TDM Slot 7
	Tight Low with 47Kohm	TDM Slot 8

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Reliability Tests

The microphone sensitivity after stress must deviate by no more than ±3dB from the initial value.

1.Heat Test, Operational	Temperature: 85±3°C Humidity: 85±5%RH Duration: 12 hours Voltage: Applied
2.Cold Test, Operational	Temperature: -40±3°C Duration: 12 hours Voltage: Applied
3.Heat Test, Non-Operational	Temperature: 85±3°C Humidity: 50±5%RH Duration: 96 hours Voltage: Not Applied
4.Cold Test, Non-Operational	Temperature: -40±3°C Duration: 96 hours Voltage: Not Applied
5.Condensation Test, Non-Operational	Temperature: 25±3°C and 55±3°C Humidity: 95±5%RH Duration: 1 hours each, during 10 minutes ramp, 45 cycles Voltage: Not applied
6.Temperature Cycling, Non-Operational	Temperature: -40±3°C and 85±3°C Humidity: 50±5% RH Duration: 2 hours each, during 6 hours ramp, 5 cycles Voltage: Not applied
7.Thermal Shock Test, Non-Operational	Temperature: -40±3°C and 85±3°C Duration: 30 minutes each, during 5 minutes ramp, 256 cycles Voltage: Not applied
8.Free Fall Test 1.5m	Placed inside test fixture and dropped on concrete from height 1.5m. (1)3 times by 6 surfaces (2)1 times by 12 edges (3)1 times by 8 corners
9.Random Vibration	Temperature: 23±5°C Humidity: 35~70% RH Duration: 2 hours each axis(X,Y,Z) Power Spectral Density: 5Hz 0.10m2/s3(=1.0391*10-3g2/Hz) 12Hz 2.20m2/s3(=22.8602*10-3g2/Hz) 20Hz 2.20m2/s3(=22.8602*10-3g2/Hz) 200Hz 0.04m2/s3(=0.41534*10-3g2/Hz) 200Hz 0.04m2/s3(=0.41564*10-3g2/Hz)
10.Repeated Low Level Free Fall Test	Placed inside test fixture and dropped on rubber mat from height of 10cm. Each face 2500 times(Total 6 faces, 15000times)
11.1m Repeated Rotating Free Fall	Placed inside test fixture and dropped on steel sheet from height of 1.0m. 100 times(all faces) Rotation speed of barrel: 10~12 falls/minute
12.Free Fall Test for master box	Corner drop: Each Corner 1 time Edge drop: Each Edge 1 time Face drop: Each Face 1 time

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13.Random Vibration for master box	Sinusoidal wave vibration Frequency: 5~50Hz Acceleration:7.4m/s2(0.76G) Sweep speed:9Hz/min(5~50Hz, one way 5 min) Test duration: Direction of Face 1-3 20min Direction of Face 2-4 20min Direction of Face 5-6 20min Sample and direction of vibration : 1 direction for 1 sample Package on vibrating table: Free
14.Substrate bending Test	Deflection: 3mm Rate: 0.5mm/sec
15.Adhesion	Load: 10 N Duration: 10 seconds
16.Electrostatic Discharge Test	Capacitance: 150pF Resistance: 330Ω Duration: 10 times Air Discharge: Level 3(+/-8kV) Direct contact discharge: Level 1 (+/-2kV)
17.Human Body Model	2000 Volts (100pF,1500Ω)
18.Charged Device Model	500 Volts
19.Self alignment effect	Displacement: 0.15mm

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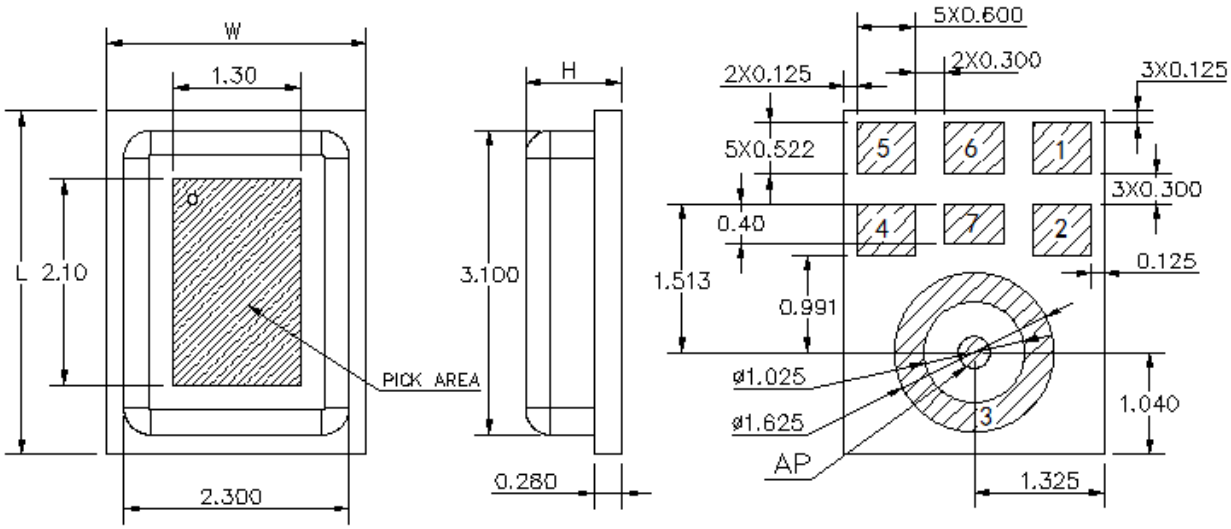
MECHANICAL SPECIFICATIOPNS



ITEM	DIMENSION	TOLERANCE	UNITS
Length (L)	3.50	±0.10	Mm
Width (W)	2.65	±0.10	Mm
Height (H)	0.98	±0.10	Mm
Acoustic Port (AP)	Ø0.325	±0.05	Mm

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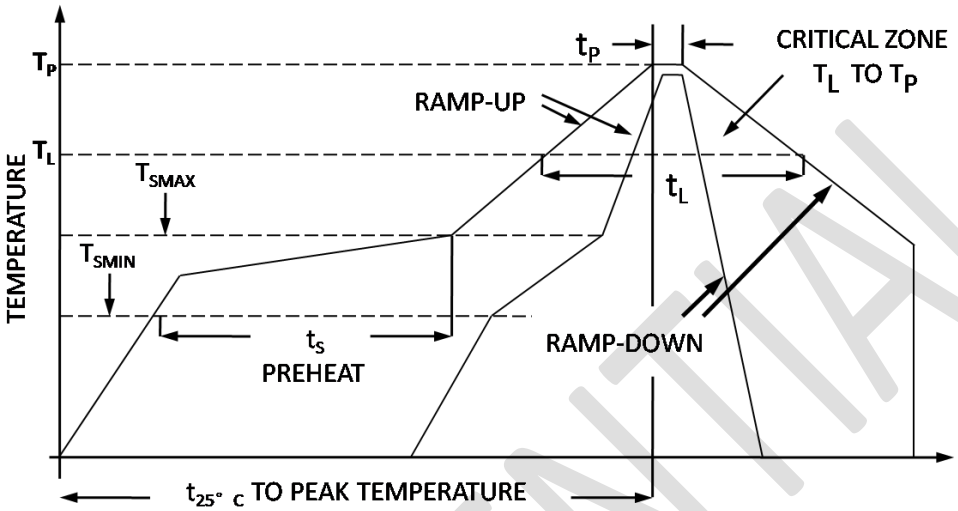
SOLDER REFLOW PROFILE

The reflow profile specified in this section describes expected maximum heat exposure of components during the reflow process of NMP product PWBs. Temperature is measured on top of component. All components have to tolerate at least this profile five times (5x) without affecting electrical performance, mechanical performance or reliability.



Pb-free and Sn63/Pb37 reflow profile requirements for soldering heat resistance:

Parameter		**Reference**	**Pb-Free**	**Sn63/Pb37**
Average Ramp Rate		T_L to T_P	3°C/sec max	1.25°C/sec max
Prehear	Minimum Temperature	T_{SMIN}	150°C	100°C
	Maximum Temperature	T_{SMAX}	200°C	150°C
	Time	T_{SMIN} to T_{SMAX}	60sec to 180sec	60sec to 75sec
Ramp-Up Rate		T_{SMAX} to T_L	1.25°C/sec	1.25°C/sec
Time Maintained Above Liquidous		t_L	~60sec	60sec to 150sec
Liquidous Temperature		T_L	217°C	183°C
Peak Temperature		T_P	260°C +0°C/-5°C	215°C +3°C/-3°C
Time Within +5°C of Actual Peak Temperature		t_P	20 sec to 40 sec	20 sec to 30 sec
Ramp-Down Rate		T_{peak}	6°C/sec max	3°C/sec max
Time +25°C (t_{25OC}) to Peak Temperature			8 min max	5 min max

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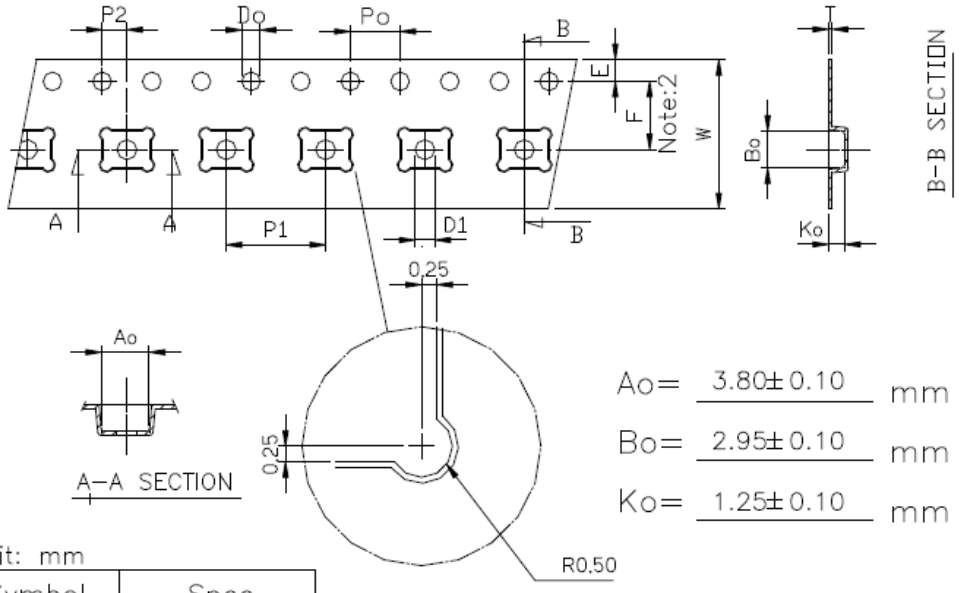
PACKAGING



Ao= 3.80±0.10 mm
Bo= 2.95±0.10 mm
Ko= 1.25±0.10 mm

Unit: mm

Symbol	Spec.
Po	4.0±0.10
P1	8.0±0.10
P2	2.0±0.10
Do	1.50 $^{+0.1}_{-0}$
D1	1.50 $^{+0.1}_{-0}$
E	1.75±0.10
F	5.50±0.10
10Po	40.0±0.10
W	12.0±0.30
T	0.30±0.05

Notice:

1. 10 Sprocket hole pitch cumulative tolerance is ±0.1mm
2. Pocket position relative to sprocket hole measured as true position of pocket not pocket hole.
3. Ao & Bo measured on a place 0.3mm above the bottom of the pocket to top surface of the carrier.
4. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
5. Carrier camber shall be not than 1mm per 100mm through a length of 250mm.

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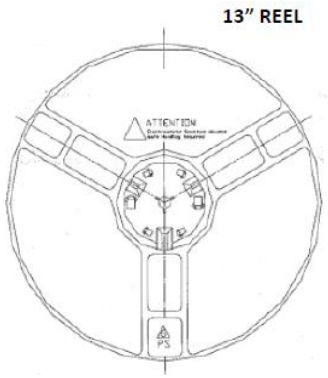
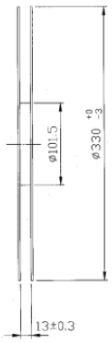
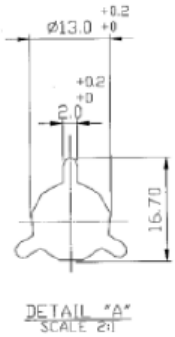
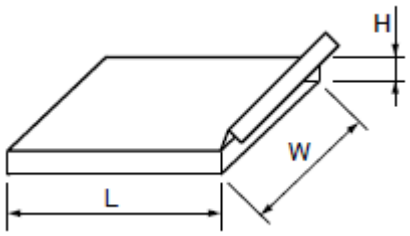






Part NO.	Reel Diameter	Quantity Per Reel	Quantity Per Inner Box	Quantity Per Outer Box
ZTS6672	13"	5200	5200	46800

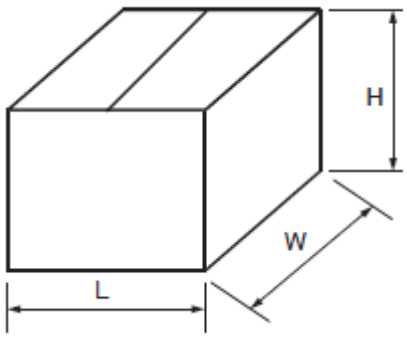
Dimensions for Inner Box



Unit：mm

L	W	H
335	339	45

Dimensions for Outer Box



Unit：mm

L	W	H
445	360	372

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